

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	4	jp-2001326326-\$ did. jp-10074891-\$ did.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2004/12/11 17:25
L2	41	(((electrode near4 (embed\$6 protrud\$6 penetrat\$6 throughhole "through-hole" (through adj hole)))) same ((wafer substrate) with (thin\$6 remov\$6 grind\$6 polish\$6 etch\$6 cmp))) same (plat\$6 electroplat\$6 electroless)) same (organic adhe\$8 peel\$6 resist photoresist paste)	US-PGPUB; USPAT	OR	ON	2004/12/11 17:26
L3	108	(438/458.ccls. 438/459.ccls. 438/667.ccls. 438/672.ccls. 438/675.ccls. 438/928.ccls. 438/977.ccls. 257/621.ccls. 257/774.ccls.) and (electrode near2 (embed\$6 protrud\$6 penetrat\$6 throughhole "through-hole" (through adj hole)))	US-PGPUB; USPAT	OR	ON	2004/12/11 17:30
L4	111	(((electrode with (embed\$6 protrud\$6 penetrat\$6 throughhole "through-hole" (through adj hole)))) and ((wafer substrate) with (thin\$6 remov\$6 grind\$6 polish\$6 etch\$6 cmp))) and (plat\$6 electroplat\$6 electroless)) and (organic adhe\$8 peel\$6 resist photoresist paste)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 17:35
L5	168	((electrode with (embed\$6 protrud\$6 penetrat\$6 throughhole "through-hole" (through adj hole)))) and ((wafer substrate) with (thin\$6 grind\$6 polish\$6 cmp))) and (plat\$6 electroplat\$6 electroless)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 17:39
L6	266	(((electrode near4 (embed\$6 protrud\$6 penetrat\$6 throughhole "through-hole" (through adj hole)))) same (plat\$6 electroplat\$6 electroless)) and (((wafer substrate) with (thin\$6 grind\$6 polish\$6 cmp)) same (organic adhe\$8 peel\$6 resist photoresist paste))	US-PGPUB; USPAT	OR	ON	2004/12/11 17:43
L7	83	(((electrode near4 (embed\$6 protrud\$6 penetrat\$6 throughhole "through-hole" (through adj hole)))) same ((wafer substrate) with (thin\$6 grind\$6 polish\$6 cmp))) same (plat\$6 electroplat\$6 electroless)	US-PGPUB; USPAT	OR	ON	2004/12/11 17:53

L8	50	(438/667.ccls 257/621.ccls.) and (438/458.ccls. 438/459.ccls. 438/672.ccls. 438/675.ccls. 438/928.ccls. 438/977.ccls. 257/774.ccls.)	US-PGPUB; USPAT	OR	OFF	2004/12/11 17:55
L9	4	ep-926723-\$.did. ep-1151962-\$.did.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2004/12/11 17:58
L10	201	438/667.ccls 257/621.ccls.	US-PGPUB; USPAT	OR	OFF	2004/12/11 17:59
L11	4	"5260169".URPN.	USPAT	OR	OFF	2004/12/11 18:02
L12	31	"5528080".URPN.	USPAT	OR	OFF	2004/12/11 18:03
L13	1	"6365513".URPN.	USPAT	OR	OFF	2004/12/11 18:03
L14	40	"4978639".URPN.	USPAT	OR	OFF	2004/12/11 18:04
L15	94	"5646067".URPN.	USPAT	OR	OFF	2004/12/11 18:05
L16	32	"5618752".URPN.	USPAT	OR	OFF	2004/12/11 18:08
L17	67	"5424245".URPN.	USPAT	OR	OFF	2004/12/11 18:09
L18	5178	438/458.ccls. 438/459.ccls. 438/667.ccls. 438/672.ccls. 438/675.ccls. 438/928.ccls. 438/977.ccls. 257/621.ccls. 257/774.ccls.	US-PGPUB; USPAT	OR	OFF	2004/12/11 18:11
L19	2758	18 and ((electrode with (embed\$6 protrud\$6 penetrat\$6 throughhole "through-hole" (through adj hole))) (via near blind) organic adhesive adhesion adher\$6)	US-PGPUB; USPAT	OR	ON	2004/12/11 18:16